



Material Content Data Sheet



Sales Product Name		TLE8250GVIO		Issued		22. January 2018		
MA#		MA001722184						
Package		PG-DSO-8-16		Weight*		83.33 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.624	3.15	3.15	31493	31493
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8607	
wire	non noble metal	copper	7440-50-8	29.121	34.95	35.86	349466	358611
	noble metal	gold	7440-57-5	0.134	0.16	0.16	1603	1603
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.11		1149
encapsulation	plastics	epoxy resin	-	4.406	5.29		52873	
	inorganic material	silicondioxide	60676-86-0	43.389	52.07	57.47	520685	574707
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9766	9766
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7803	7803
glue	plastics	acrylic resin	-	0.294	0.35		3524	
	noble metal	silver	7440-22-4	1.041	1.25	1.60	12493	16017
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com